



SUNLU Filaments Parameters

Material	Printing Temp. (°C)	Platform Temp. (°C)	Bedding plate (°C)	Thermal Deformation Temp. (°C)	Melt Mass Flow Rate	Density (g/cm ³)	Tensile Strength (MPa)	Resilience Elongation (%)	Water Absorption (%)	Tolerance
PLA	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	55	7-9g/10min (100°C, 2.18kg)	1.24	11-12	4	0.50%	±0.02mm
PLA+	210-235	70-100°C	100-100	57	9-11g/10min (90°C, 2.18kg)	1.24	11-12	45	0.50%	±0.02mm
PLA Soft Layer	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	55	7-9g/10min (100°C, 2.18kg)	1.24	11-12	4	0.50%	±0.02mm
PA6	200-240	1. No need when with glue stick 2. 60-80°C without glue stick	140-140	54	11-13g/10min (100°C, 2.18kg)	1.14	8-9	110	0.10%	±0.02mm
PLA Carbon Fiber	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	55	7-9g/10min (100°C, 2.18kg)	1.24	11-12	4	0.70%	±0.02mm
ABS	240-260	Get metal cooling with Infrared insulation and semi sealed?	100-100	54	10-11g/10min (220°C, 1.98kg)	1.18	4-11	45	1.10%	±0.02mm
ABS High Temp.	250-270	Get metal cooling with Infrared insulation and semi sealed?	100-100	55	10-11g/10min (220°C, 1.98kg)	1.17	6-13	20	1.10%	±0.02mm
ABS Resistant	250-270	Get metal cooling with Infrared insulation and semi sealed?	100-100	57	10-11g/10min (220°C, 1.98kg)	1.18	6-11	19	1.10%	±0.02mm
HTD	200-270	Get metal cooling with Infrared insulation and semi sealed?	100-100	51	10-11g/10min (200°C, 1.98kg)	1.15	5-7	31	1.30%	±0.02mm
PC/PC	200-230	1. No need when with glue stick 2. 70-80°C without glue stick	100-100	55	6-11g/10min (200°C, 2.18kg)	1.25	6-4	210	0.30%	±0.02mm
WASA	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	51	6-11g/10min (200°C, 2.18kg)	1.33	6-13	4	1.70%	±0.02mm
TPU	200-230	No need	100-100	+	11-13g/10min (100°C, 2.18kg)	1.17	7	600	0.70%	±0.02mm
PA	240-260	Get metal cooling with Infrared insulation and semi sealed?	100-100	56	10-11g/10min (200°C, 2.18kg)	1.13	5-7	200	0.60%	±0.02mm
PE	200-230	Get metal cooling with Infrared insulation and semi sealed?	100-100	59	10-11g/10min (220°C, 2.18kg)	1.1	5-6	110	0.30%	±0.02mm
ASA	240-260	1. No need when with glue stick 2. 60-80°C without glue stick	140-140	+	10-11g/10min (200°C, 2.18kg)	1.14	5-11	30%	0.10%	±0.02mm
PC	200-230	No need	50-50	+	11-13g/10min (200°C, 2.18kg)	1.21	7	200	0.70%	±0.02mm
TPU40	200-240	Get metal cooling with Infrared insulation and semi sealed?	100-100	52	9-10g/10min (220°C, 2.18kg)	1.19	6-12	12	0.60%	±0.02mm
ASA	250-280	Get metal cooling with Infrared insulation and semi sealed?	100-100	55	9-10g/10min (220°C, 2.18kg)	1.14	6-10	24	1.30%	±0.02mm
PLA Carbon Fiber	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	52	11-13g/10min (220°C, 2.18kg)	1.2	11-11	3	0.50%	±0.02mm